

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc2937cuhe#pbf

(Engineering Calculation)

QFN 5mm X 6mm Exp.Pad

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TOTAL MASS (g) : 0.073268

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.005041 | 1000000 | 68802.0625 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.025794 | 975000 | 352049.28125 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000635 | 24000 | 8666.79492188 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000008 | 299.999908447 | 109.187965393 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000019 | 700 | 259.321411133 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.026456 | 1000000 | 361084.625 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.001276 | 1000000 | 17417.5507812 | | |
| | | External Plating Total: | | | | 0.001276 | 1000000 | 17417.5507812 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000573 | 1000000 | 7820.58837891 | | |
| Internal Plating Total: | | | | 0.000573 | 1000000 | 7820.58837891 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001758 | 750000 | 23994.0566406 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000586 | 250000 | 7998.01855469 | | |
| Die Attach Total: | | | | 0.002344 | 1000000 | 31992.0742188 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.004876 | 130000 | 66550.0703125 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.032257 | 860000 | 440259.5625 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000375 | 10000 | 5118.18603516 | | |
| | | Encapsulation Total: | | | | 0.037508 | 1000000 | 511927.78125 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000070 | 1000000 | 955.394775391 | | |
| | | | | | TOTAL MASS (g) : | 0.073268 | | |